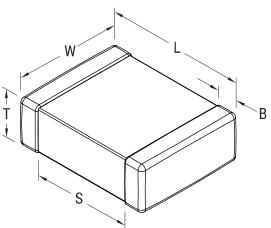


C0805C334K5REC7210

General Information

ESD SMD Comm X7R, Ceramic, 0.33 uF, 10%, 50 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 0805, 0.7 mm





	Series	ESD SMD Comm X7R
	Style	SMD Chip
В	Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II
	Features	Temperature Stable, Class II
	RoHS	Yes
	Termination	Tin
	Marking	No
	AEC-Q200	No
	Typical Component Weight	13 mg
	Shelf Life	78 Weeks
	MSL	1

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	0.9mm +/-0.10mm
S	0.7mm MIN
В	0.5mm +/-0.25mm

Click here for the 3D model.

Packaging Specifications	
Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	15000

Specifications	
Capacitance	0.33 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	50 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	1.5152 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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